

LOCTITE ABLESTIK 24

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PRODUCT DESCRIPTION

LOCTITE ABLESTIK 24 provides the following product characteristics:

Technology	Epoxy
Appearance	Water clear
Components	Two components - requires mixing
Mix Ratio, by weight Part A: Part B	100 : 28
Product Benefits	• Two component • Low viscosity • Room temperature cure • Easy mixing • Flexible • Resilient bonds between materials with mismatched CTEs
Operating Temperature - Continuous	90 °C
Operating Temperature - Intermittent	120°C
Cure	Room temperature cure
Application	Assembly, Non electrically conductive adhesive
Key Substrates	Most metals, Ceramics, Polystyrene, Polysulfone, Polycarbonate and Rigid plastics

LOCTITE ABLESTIK 24 is recommended for joining transparent materials, such as glass, and where a thin bond line is desired. This adhesive can withstand continuous exposure at temperatures as high as 90°C and short term exposures up to 120°C.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Mixed Properties

Mixed Viscosity @ 25 °C, mPa·s (cP)	800
Pot life @ 25°C, 50 gram quantities, minutes	30
Shelf Life - See C of A or Label on packaging	
Flash Point - See SDS	

TYPICAL CURING PERFORMANCE

Cure Schedule

1 to 3 hours @ 25°C

Full properties are developed in 16 to 24 hours.

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

Thermal Conductivity, W/(m·K)	0.2
Coefficient of Linear Thermal Expansion, ppm/°C	60

Electrical Properties

Volume Resistivity @ 25°C, ohm-cm	1×10 ¹⁴
Dielectric Strength, ASTM D149, kV/mm	16.5

TYPICAL PERFORMANCE OF CURED MATERIAL

Shear Strength

Tensile Lap Shear Strength,	N/mm ²	12
	(psi)	(1,740)

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

DIRECTIONS FOR USE

1. Complete cleaning of the substrates should be performed to remove contamination such as oxide layers, dust, moisture, salt and oils which can cause poor adhesion or corrosion in a bonded part.
2. Clean up solvent is alcohol, acetone, or methyl ethyl ketone (MEK).
3. Vapor de-greasing is satisfactory.
4. Roughening of the surfaces will improve bond strength.
5. Accurately weigh resin and hardener into a clean container in the recommended ratio. Weighing apparatus having an accuracy in proportion to the amounts being weighed should be used.
6. In small quantities, a 4:1 ratio by weight or 3:1 ratio by volume is acceptable.
7. Mix thoroughly.
8. Coat both surfaces to be joined with as thin a layer of adhesive as possible and join together.
9. In most applications only contact pressure is required.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

STORAGE:

Store in original, tightly covered containers in clean, dry areas. Storage information may be indicated on the product container labeling.

Optimal Storage : 18 to 25 °C

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$
 $\text{kV/mm} \times 25.4 = \text{V/mil}$
 $\text{mm} / 25.4 = \text{inches}$
 $\text{N} \times 0.225 = \text{lb/F}$
 $\text{N/mm} \times 5.71 = \text{lb/in}$
 $\text{psi} \times 145 = \text{N/mm}^2$
 $\text{MPa} = \text{N/mm}^2$
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$
 $\text{mPa}\cdot\text{s} = \text{cP}$

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